



Superior Technologies Yield Superior Solutions.

There's always a better solution. A faster way to achieve quality results. A more efficient route. A superior way to simplify complex processes. And we're determined to be that company that uncovers it and puts it to use for you. To that end, we invest millions each year in research and development and collaborate with leading industry partners so that you can achieve your goals of creating next-generation products faster, easier, and with superior results. Contact us for help with:

Signal Integrity • Power Distribution • Thermal Management
RF & Microwave • High Density Interconnects • DFM Analysis • ATE / Burn in Boards

Technical Capabilities

Materials:

Laminate & Prepreg per IPC4101 and IPC-CF-150E
Material types used: High Temp and Enhanced multifunctional FR-4, Halogen-free FR4, FR370-HR, Getek, Polyimide, BT, CE, Isola 408, Nelco 4000 series, Rogers, BC2000™, Ohmega Ply, Arlon, StablCor® ST-10
Max. panel size: 24" x 27"
Laser Direct Imaging:
Orbotech
Layers imaged direct from CAM data
Resolution to <2 mil
Automatic Optical Inspection:
Orbotech 309 Blazers & Discovery™ 8
Maxsys automated verification stations
CAD reference to CAD data
¼ mil resolutions and variance detection
Verification of desired line width
Layer Construction/
Impedance Design:
Min. core thickness: .002"
Min. dielectric: .0015"
Impedance stack-up design and verification service
Buried & Blind Microvias
Stacked Microvias SMV™
Flat Wrap™ Technology
Sequential lamination construction
Buried Capacitance
Buried Resistance
Finished impedance tolerance of +/- 5 %

Lamination:

Max. number of layers: 60
Max. board thickness: .300"
Min. MLB thickness: .010"
Drilling:
Yag & CO2 laser MicroVia capability
Min. drilled hole size: .004"
Max. drilled hole size: .257"
Max. routed hole size: 24"
Min. slot width size: .020"
Min. plane clearance must be greater than nominal finished hole: .020"
Control depth drill
Plating:
Max. hole aspect ratio: 16:1
Selective solder strip / fuse for tight pitch TAB and BGA
SMOBC
SMOBC with OSP, Enthone, CU56, CU106a, MacDermid M-Plus, Kester
Immersion, Electroless & Electrolytic Gold
Immersion Silver, Nickel / Palladium / Gold
Lead free HASL
Multiple surface plating
Soldermask:
Per IPC-SM-840
Wet types: SR1000, SR1001
Photo-imageable types:
Taiyo PSR-4000, Dynachem, Enthone, Dexter Hysol 8200, Lea Ronal, Coates Clear
LDI Soldermask
Dryfilm types: Dupont Vacreil 8000 series
Conductive and non-conductive via fill

Fabrication:

Tolerance on overall dimensions: +/- .005"
Min. inside radius: .015"
Scoring, In-board Beveling, Beveling
Countersinking, Counterboring, Edge Milling
Electrical Test:
ECT, TTI, Mania, Microcraft Testers
ATG High Speed Flying Probe Testers
Computer Aided test engineering work stations
Gerber extracted net-list testing
Gerber extracted buried resistor testing
CAD net-list testing (IPC-356A)
Electrical test parameters compliant with IPC and Bellcore specifications
Standard SMD pitch to: .016"
Flying Probe pitch to .004"

Quality System & Certifications:

- ISO 9001-2000 certified
- IPC-600, 6011/ 6012
- MIL-P-55110
- PRF-31032
- MIL-P-50884
- MIL-P-50884
- NASA
- WS-6536
- ELV
- AS-9100
- NADCAP

Locations

1220 N. Simon Circle
Anaheim, CA 92086
714-688-7200

1992 Tarob Court
Milpitas, CA 95035
408-263-0940

3471B McNicoll Avenue
Toronto, ON Canada
416-283-4888

1200 Severn Way
Sterling, VA 20166
703-652-2202

www.ddiglobal.com need a quote? Salesinfo@ddiglobal.com

NORANA

DIŞ TİCARET VE MÜMESSİLLİK LTD. ŞTİ.



Atatürk Caddesi 206, Kat 1, Alsancak, 35220 İzmir, Türkiye
Telf: (232) 464-0011 Fax: (232) 463-0673
Email : norana@norana.com.tr www.norana.com.tr